

**PATENT APPLICATION**  
**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of

Docket No: Q78657

Hien Boon TAN , et al.

Appln. No.: 10/581,395

Group Art Unit: 2818

Confirmation No.: 3868

Examiner: David J GOODWIN

Filed: August 14, 2008

For: CHIP SCALE PACKAGE AND METHOD OF ASSEMBLING THE SAME

**AMENDMENT UNDER 37 C.F.R. § 1.111**

**MAIL STOP AMENDMENT**

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Sir:

In response to the Office Action dated August 3, 2009, please amend the above-identified application as follows on the accompanying pages.

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